

**In the Claims**

**The claims have been amended as follows:**

1     1.     (Currently Amended) A method to enhance integrated circuit device heat  
2     dissipation comprising the steps of:

3           providing an integrated circuit device having a surface;

4           providing a flexible corrugated tape strip of a thermal conductive material having a flat

5           flexible tape strip of a thermal conductive material bonded to ~~one~~ each side

6           thereto forming a ~~single~~ double-faced flexible corrugated tape strip article; and

7           adhering the double-faced flexible corrugated tape strip article to the surface of the

8           integrated circuit device.

1     2.     (Canceled)

1     3.     (Currently Amended) The method of claim 1 wherein ~~the~~ both tape strips ~~is~~ are  
2     metal and ~~is~~ copper or aluminum.

1     4.     (Previously presented) The method of claim 3 wherein the thickness of the tape  
2     strip used to make the corrugated tape strip and the flat flexible tape strip are both about  
3     0.5 mil to 10 mil.

1        5.        (Withdrawn) The method of claim 4 wherein the corrugated strip has corrugations  
2        in the shape of a repeating series of triangles.

1        6.        (Original) The method of claim 4 wherein the corrugations in the strip are in the  
2        shape of a repeating series of convex and concave portions comprising sidewall portions,  
3        top portions and bottom portions.

1        7.        (Withdrawn) The method of claim 4 wherein the corrugations in the strip are in  
2        the shape of a repeating series of convex portions comprising angled sidewalls and a top  
3        portion and a triangular concave portion.

1        8.        (Withdrawn) The method of claim 4 wherein the corrugations in the strip are in  
2        the shape of a series of vertical fins.

1        9.        (Withdrawn) The method of claim 4 wherein the corrugating in the strip are in the  
2        shape of a repeating series of loops.

1        10.       (Withdrawn) The method of claim 1 wherein the flexible corrugated strips have an  
2        adhesive thereon to adhere the corrugated strip to the integrated circuit device.

1        11.       (Canceled)

12. (Withdrawn) The method of claim 1 wherein the flat flexible tape strip article has an adhesive thereon on the side to be adhered to the integrated circuit device.

13. (Canceled)

14. (Withdrawn) The method of claim 13 wherein at least one of the flat flexible strips has an adhesive on the side to be adhered to the integrated circuit device.

15. (Withdrawn) The method of claim 14 wherein each side of the flat flexible strips has an adhesive thereon for adhering to an integrated circuit device.

16. (Currently Amended) A method to enhance integrated circuit device heat dissipation comprising the steps of:

providing an integrated circuit device having a surface;

providing a tape strip of flexible flat thermal conductive material;

forming corrugations in the tape strip of the flexible thermal conductive material;

bonding a thermal conductive material flat tape strip to ~~one~~each side of the flexible corrugated tape strip forming a ~~single~~double-faced flexible corrugated tape strip article; and

adhering the ~~single~~double-faced flexible corrugated tape strip article to the surface of the integrated circuit device.

1 17. (Withdrawn) The method of claim 16 wherein an adhesive is applied to the strip  
2 surface before corrugation.

1 18. (Withdrawn) The method of claim 16 wherein an adhesive is applied to a strip  
2 surface after corrugation.

1 19. (Canceled)

1 20. (Withdrawn) The method of claim 19 wherein an adhesive is applied to the side  
2 of a single-faced corrugated strip to be adhered to an integrated circuit device.

1 21. (Canceled)

1 22. (Withdrawn) The method of claim 21 wherein an adhesive is applied to the side  
2 of the double-faced corrugated strip to be adhered to an integrated circuit device.

1 23. (Withdrawn) The method of claim 22 wherein an adhesive is applied to each side  
2 of the double-faced corrugated tape article.

1 24. (Currently Amended) An article of manufacture for dissipating heat for integrated  
2 circuit devices comprising a corrugated flexible tape strip of thermal conductive material  
3 having a flat flexible tape strip of a thermal conductive material bonded to one side ~~each~~  
4 thereto forming a ~~single~~ double-faced flexible corrugated tape strip article.

1 25.-26. (Canceled)

1 27. (Withdrawn) The article of claim 26 wherein the flat tape strip of thermal  
2 conductive material has an adhesive on the side to be adhered to an integrated circuit  
3 device.

1 28. (Canceled)

1 29.-34. (Canceled)

1 35. (New) A method to enhance integrated circuit device heat dissipation comprising  
2 the steps of:

3 providing an integrated circuit device having a surface;

4 providing a flexible corrugated tape strip of a thermal conductive material having a flat

5 flexible tape strip of a thermal conductive material bonded to one side thereto

6 forming a single-faced flexible corrugated tape strip article; and

7 adhering the single-faced flexible corrugated tape strip article to the surface of the

8 integrated circuit device.